



Material Content Data Sheet



Sales Product Name		ESD103-B1-02ELS E6327		Issued		19. July 2018		
MA#		MA001100018						
Package		PG-TSSLP-2-4		Weight*		0.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.33		3268	
	noble metal	gold	7440-57-5	0.003	1.27		12681	
	inorganic material	silicon	7440-21-3	0.020	9.40	11.00	93964	109913
leadframe	non noble metal	nickel	7440-02-0	0.108	50.67	50.67	506732	506732
wire	noble metal	gold	7440-57-5	0.003	1.29	1.29	12949	12949
encapsulation	organic material	carbon black	1333-86-4	0.000	0.16		1641	
	plastics	epoxy resin	-	0.010	4.75		47537	
	inorganic material	silicondioxide	60676-86-0	0.059	27.87	32.78	278660	327838
leadfinish	noble metal	gold	7440-57-5	0.004	1.73	1.73	17290	17290
plating	noble metal	palladium	7440-05-3	0.001	0.60		5996	
	noble metal	gold	7440-57-5	0.004	1.93	2.53	19282	25278
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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